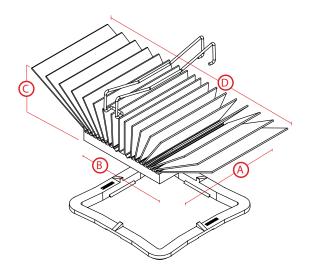


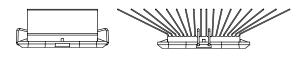
Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-50400P-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance thermal interface material
- » Designed for standard height components from 3 to 4.5mm





*Image above is for illustration purposes only.

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE		
M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)		
1.0	2	1.6		
1.5	1.6			
2.0	1.4			
2.5	1.2			
3.0	1.1			
3.5	1.1			
4.0	1			
	M/S 1.0 1.5 2.0 2.5 3.0 3.5	M/S °C/W (UNDUCTED FLOW) 1.0 2 1.5 1.6 2.0 1.4 2.5 1.2 3.0 1.1 3.5 1.1		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
40 mm	40 mm	17.5 mm	69.1 mm	SAINT-GOBAIN C675	BLUE-ANODIZED

NOTES

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT400
- 5) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).